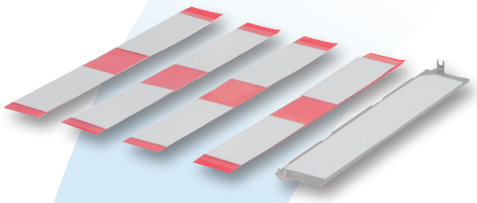
Laird TECHNOLOGIES

Innovative **Technology** for a **Connected** World

Tflex™ 200T V0 Series
Thermal Gap Filler



THIN THERMALLY CONDUCTIVITY ELASTOMERIC INTERFACE MATERIAL

Tflex™ 200T V0 is a specially formulated thin gap filler thermal interface material designed for thin interfaces that require a combination good thermal performance with great reliability. The elastomeric property of Tflex™ 200T V0 provides good thermal performance in a thin interface where reliability, shock and vibration considerations, are critical performance considerations in addition to low thermal resistance.

Tflex™ 200T V0's unique silicone and ceramic filler technology allows a combination of great reliability, good thermal performance, and easy handling.

Tflex™ 200T V0 is slightly tacky, and requires no additional adhesive coating that inhibits thermal performance. Tflex™ 200T V0 is electrically insulating, stable from -40ºC thru 200ºC and meets UL 94V0 flame rating.

FEATURES AND BENEFITS

- Thermal Conductivity 1.5 W/mK
- Compliant Elastomeric based thin interface material
- Available in 0.008-inch (0.2mm), 0.010-inch (0.25mm), 0.012-inch (0.30mm), 0.015-inch (0.38mm) , and 0.020-inch (0.51mm) thicknesses
- Slightly tacky for adhesion during assembly and transport
- Competitive price for high volume applications
- Available as individual custom parts, sheets, or custom parts converted on a roll

APPLICATIONS

- Memory Modules:
  DDR2, DDR3, SDRAM, SRAM, RAM, NVRAM
- LED solid state lighting
- Power electronics

global solutions: local support™

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	8 MIL	10 MIL	15 MIL	TEST METHOD
Construction & Composition	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer, reinforced	
Color	Light Grey	Light Grey	Light Grey	Visual
Thickness	0.008" (0.203mm)	0.010" (0.254mm)	0.015" (0.381mm)	
Thickness tolerance	±0.0015" (±0.038mm)	±0.0015" (±0.038mm)	±0.00225" (±0.057mm)	
Specific Gravity (Density)	2.32 g/cc	2.32 g/cc	2.32 g/cc	Helium Pycnometer
Hardness (Shore 00)	55	55	55	ASTM D2240
Outgassing TML (Post Cured)	0.38%	0.38%	0.38%	ASTM E595
Outgassing CVCM (Post Cured)	0.11%	0.11%	0.11%	ASTM E595
UL Flammability Rating	94 V0	94 V0	94 V0	E180840
Temperature Range	-45°C to 200°C	-45°C to 200°C	-45°C to 200°C	
Thermal Conductivity	1.5 W/mK	1.5 W/mK	1.5 W/mK	Hot Disk
Thermal Impedance @ 10 psi @ 69 KPa	0.384°C-in²/W 2.48°C-cm²/W	0.488°C-in²/W 3.14°C-cm²/W	0.714°C-in²/W 4.60°C-cm²/W	ASTM D5470 (modified)
Thermal Expansion (30-150°C)	231.19ppm/°C	231.19ppm/°C	231.19ppm/°C	IPC-TM-650 2.4 2.4
Volume Resistivity	$3.5x10^{10}$ ohm-cm	$3.5x10^{10}$ ohm-cm	$3.5x10^{10}$ ohm-cm	ASTM D257
Dielectric Constant @ 1 MHz	5.0	5.1	5.1	ASTM D150

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.